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REPLY UNDER 37 CFR §1.116
EXPEDITED PROCEDURE
TECHNOLOGY CENTER 2800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:
William Hong, et al.

Serial No.: 10/714,985

Filed: November 17, 2003

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Attorney Docket No.
2003.0299 / 24061.514

Customer No. 42717

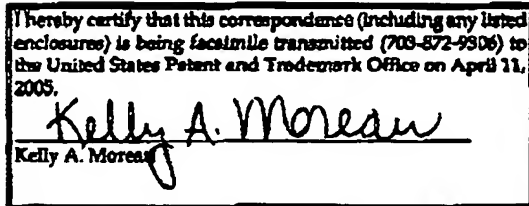
Group Art Unit: 2813

Examiner: Thanh T. Nguyen

Confirmation No.: 2268

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Sir:



RESPONSE UNDER 37 CFR §1.116

This Response is submitted in reply to the Office Action mailed on February 2, 2005.
(Please see the pages that follow).